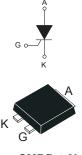


# X0115MUF

Datasheet

# 1 A sensitive gate SCR thyristor



SMBflat-3L

### **Features**

- On-state rms current, 1 A
- Narrow sensitive gate current from 30 μA to 150 μA
- Repetitive peak off-state voltage, 600 V
- Non-repetitive surge peak off-state voltage, 750 V
- Compact and ultraflat SMBflat-3L package with creepage distance of 3.4 mm

### **Applications**

- Ground-fault circuit interrupter (GFCI, RCB, RCD)
- Arc-fault circuit interrupter (AFCI)
- Overvoltage crowbar protection in power supplies
- Capacitive ignition circuits
- Low consumption triggering switches

### **Description**

Thanks to highly sensitive triggering levels, the 1 A X0115MUF SCR thyristor is suitable for all applications where available gate current is limited. The X0115MUF offers a high blocking voltage of 600 V, and a surge peak voltage of 750 V, ideal for applications like ground fault circuit interrupter (GFCI) and arc fault circuit interrupters (AFCI).

The surface mount SMBflat-3L package allows modern, compact, SMD based designs for automated manufacturing. Its 3.4 mm creepage distance guarantees a 250 V functional isolation (UL 840) at a level 2 pollution degree.

| Product status link                |        |  |  |
|------------------------------------|--------|--|--|
| X0115MUF                           |        |  |  |
| Product summary                    |        |  |  |
| I <sub>T(RMS)</sub> 1 A            |        |  |  |
| V <sub>DRM</sub> /V <sub>RRM</sub> | 600 V  |  |  |
| T <sub>j(max.)</sub>               | 125 °C |  |  |

# 1 Characteristics

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| Symbol                              | Value  | Unit                   |                        |             |                  |
|-------------------------------------|--|------------------------|------------------------|-------------|------------------|
| I <sub>T(RMS)</sub>                 | On-state RMS current (180° conduction angle)   |                        |                        | 1           | А                |
| I <sub>T(AV)</sub>                  | Average on-state current (180° conduction angle)   |                        |                        | 0.64        | А                |
|                                     | Non repetitive surge peak on-state current $t_p = 8.3 \text{ ms}$                                    |                        | T <sub>i</sub> = 25 °C | 12          |                  |
| ITSM                                | (T <sub>j</sub> initial = 25 °C)   | t <sub>p</sub> = 10 ms | 1j = 25°C              | 11          | A                |
| l <sup>2</sup> t                    | $I^{2}t$ value for fusing $t_{p} = 10 \text{ ms}$  |                        | T <sub>j</sub> = 25 °C | 0.60        | A <sup>2</sup> s |
| dl/dt                               | Critical rate of rise of on-state current<br>$I_G = 2 \times I_{GT}$ , $t_r \le 100$ ns<br>F = 60 Hz |                        | T <sub>j</sub> = 25 °C | 75          | A/µs             |
| V <sub>DRM</sub> / V <sub>RRM</sub> | Repetitive peak off-state voltage $T_j = 125 \text{ °C}$   |                        |                        |             | V                |
| V <sub>DSM</sub> / V <sub>RSM</sub> | Non repetitive surge peak off-state voltage $t_p = 10 \text{ ms}$                                    |                        | T <sub>j</sub> = 25 °C | 750         | V                |
| I <sub>GM</sub>                     | Peak forward gate current $t_p = 20 \ \mu s$ $T_j = 1$   |                        |                        | 1.2         | Α                |
| P <sub>G(AV)</sub>                  | Average gate power dissipation   | 0.2                    | W                      |             |                  |
| T <sub>stg</sub>                    | Storage junction temperature range   | -40 to +150            | °C                     |             |                  |
| Tj                                  | Operating junction temperature range   |                        |                        | -40 to +125 | °C               |

### Table 1. Absolute maximum ratings (limiting values)

### Table 2. Electrical characteristics (T<sub>j</sub> = 25 °C, unless otherwise specified)

| Symbol          | Parameters  | Va   | Unit |      |
|-----------------|---|------|------|------|
|                 |   | Min. | 30   | μΑ   |
| I <sub>GT</sub> | $V_{D}$ = 12 V, R <sub>L</sub> = 140 $\Omega$   | Max. | 150  |      |
| V <sub>GT</sub> |   | Max. | 0.8  | V    |
| $V_{GD}$        | $V_D = V_{DRM}$ , $R_L = 3.3 \text{ k}\Omega$ , $R_{GK} = 1 \text{ k}\Omega$ , $T_j = 125 \text{ °C}$ |      | 0.2  | V    |
| V <sub>RG</sub> | I <sub>RG</sub> = 10 μA   |      | 5    | V    |
| Ι <sub>Η</sub>  | I <sub>T</sub> = 50 mA, R <sub>GK</sub> = 1 kΩ  |      | 5    | mA   |
| ١L              | $I_G = 1.2 I_{GT}, R_{GK} = 1 k\Omega$  |      | 6    | mA   |
| dV/dt           | $V_D$ = 67 % $V_{DRM}$ , $R_{GK}$ = 1 k $\Omega$ , $T_j$ = 125 °C                                     | Min. | 80   | V/µs |

### Table 3. Static characteristics

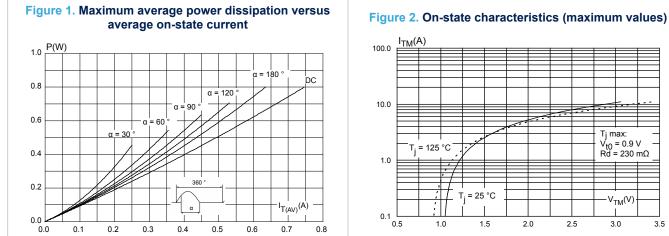
| Symbol                              | Symbol Test conditions                             |                         |      | Value |    |
|-------------------------------------|--|-------------------------|------|-------|----|
| V <sub>T</sub>                      | I <sub>TM</sub> = 2.0 A, t <sub>p</sub> = 380 μs   | T <sub>j</sub> = 25 °C  | Max. | 1.40  | V  |
| V <sub>TO</sub>                     | Threshold on-state voltage                         | T <sub>j</sub> = 125 °C | Max. | 0.90  | V  |
| R <sub>d</sub>                      | Dynamic resistance                                 | T <sub>j</sub> = 125 °C | Max. | 230   | mΩ |
| I <sub>DRM</sub> / I <sub>RRM</sub> | $V_D = V_{DRM}, V_R = V_{RRM}, R_{GK} = 1 k\Omega$ | T <sub>j</sub> = 25 °C  |      | 1     | μA |
|                                     |  | T <sub>j</sub> = 125 °C | Max. | 150   | μA |

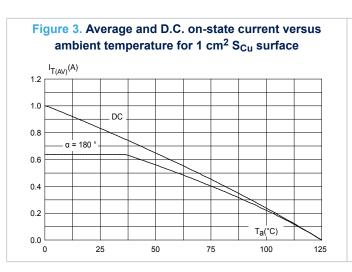
### Table 4. Thermal resistance

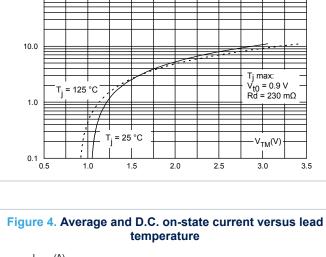
| Symbol               | Parameters  | Value | Unit |
|----------------------|---|-------|------|
| R <sub>th(j-l)</sub> | Junction to lead (DC)   | 15    | °C/W |
| R <sub>th(j-a)</sub> | Junction to ambient (DC) for 5 cm <sup>2</sup> copper surface | 75    | 0/00 |

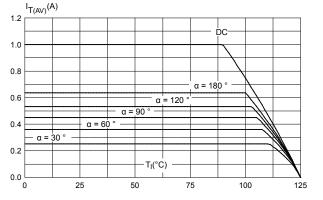
### 1.1 **Characteristics (curves)**

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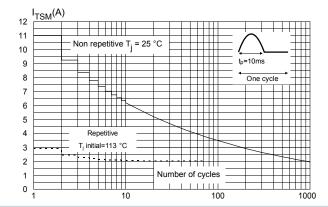
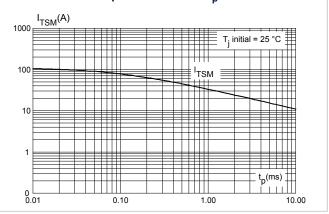
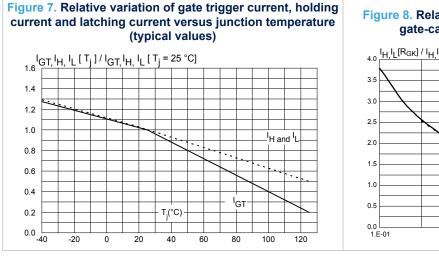


Figure 6. Non repetitive surge peak on-state current for a sinusoidal pulse with width t<sub>p</sub> < 10 ms







# Figure 8. Relative variation of holding current versus gate-cathode resistance (typical values)

# Figure 9. Relative variation of static dV/dt immunity versus junction temperature

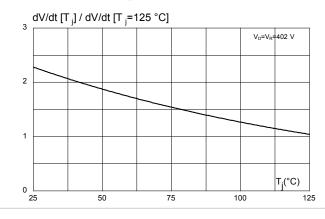
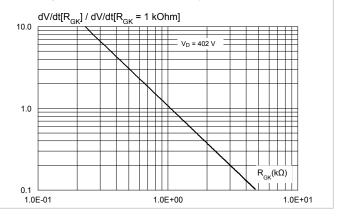
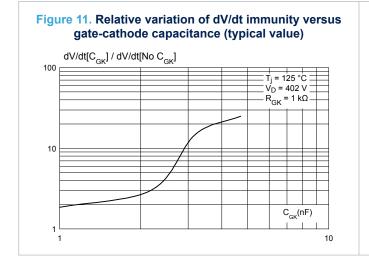
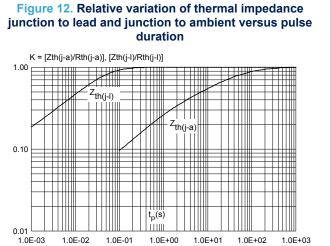
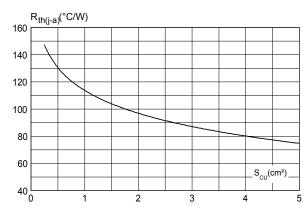


Figure 10. Relative variation of dV/dt immunity versus gate-cathode resistance (typical values)









### Figure 13. Typical thermal resistance junction to ambient versus copper surface under anode (epoxy FR4, $e_{CU}$ = 35 µm, SMBflat-3L)

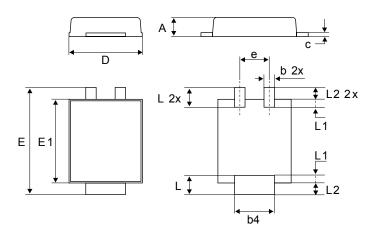
# 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SMBflat-3L package information

- Epoxy meets UL94, V0
- Lead-free package

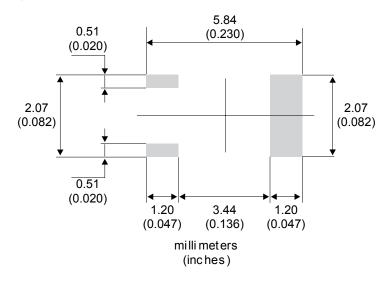
Figure 14. SMBflat-3L package outline



Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions in the following table are guaranteed.

### Table 5. SMBflat-3L mechanical data

|      | Dimensions |             |      |  |        |        |
|------|------------|-------------|------|--|--------|--------|
| Ref. |            | Millimeters |      | Inches (dimensions are for reference only) |        |        |
|      | Min.       | Тур.        | Max. | Min.                                       | Тур.   | Max.   |
| A    | 0.90       |             | 1.10 | 0.0354                                     |        | 0.0433 |
| b    | 0.35       |             | 0.65 | 0.0138                                     |        | 0.0256 |
| b4   | 1.95       |             | 2.20 | 0.0768                                     |        | 0.0866 |
| С    | 0.15       |             | 0.40 | 0.0059                                     |        | 0.0157 |
| D    | 3.30       |             | 3.95 | 0.1299                                     |        | 0.1555 |
| E    | 5.10       |             | 5.60 | 0.2008                                     |        | 0.2205 |
| E1   | 4.05       |             | 4.60 | 0.1594                                     |        | 0.1811 |
| L    | 0.75       |             | 1.50 | 0.0295                                     |        | 0.0591 |
| L1   |            | 0.40        |      |  | 0.0157 |        |
| L2   |            | 0.60        |      |  | 0.0236 |        |
| е    |            | 1.60        |      |  | 0.0630 |        |



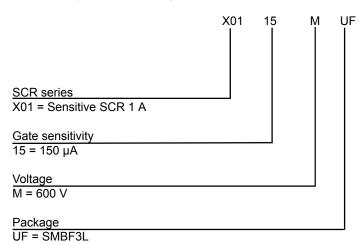
### Figure 15. Footprint recommendations, dimensions in mm (inches)

Note: This drawing may not be in scale; however, all the specified dimensions are guaranteed.



# **3** Ordering information

### Figure 16. Ordering information scheme



### Table 6. Ordering information

| Order code | Marking | Package    | Weight | Base qty. | Delivery mode |
|------------|---------|------------|--------|-----------|---------------|
| X0115MUF   | X1M     | SMBflat-3L | 47 mg  | 5000      | Tape and reel |

## **Revision history**

### Table 7. Document revision history

| Date        | Revision | Changes   |
|-------------|----------|---|
| 30-Jul-2019 | 1        | First issue.  |
| 10-Oct-2019 | 2        | Updated Table 2. Electrical characteristics ( $T_j$ = 25 °C, unless otherwise specified). |



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